

T-8

*Inorganic Hot Tinning
Water Soluble Liquid Flux*



Product Description

T-8 is an inorganic acid flux. It is very active flux of zinc-ammonium type. T-8 is a fumeless and flammable aqueous solution designed to restore the solderability of tarnished copper surface especially for hot solder dipping process. The advantage over tin plating or other metallic plating is a thicker, non-porous coating without organic inclusions in which a metallurgical bond is formed with the base metal. Innovative technology from Asahi has resulted in the development of T-8 for use in the hot solder dipping process. The flux residue can be completely removed with thorough water rinse providing copper wire surface free from ionic contamination.

Application

The copper wire is first applied through the flux pot which contains T-8. After fluxing, no pre-heating is required and the surface of the copper wire is cleaned by passing the wire through a wet cloth before wire is conveyed through the bath of molten solder.

Residue Removal

The residue left after soldering is hygroscopic and ionisable. Complete residue removal immediately after soldering is recommended. Removal of the residue can best be achieved with water at a minimum temperature of 40°C, followed by a final deionised water rinse.

Recommended Solvent

No solvent is required.

Health and Safety

Observe standard precautions for handling and use, such as well-ventilated areas and avoidance of prolonged or repeated contact with the skin. For more information, please refer to the Material Safety Data Sheet.

Specification

Item	Result
State	Liquid
Colour	Colourless
Specific Gravity @ 23°C	0.806 +/- 0.01
<small>JIS Z 3197 8.2.2</small>	
Non-volatile Solid Content (110°C, 3hr)	2.0 +/- 0.5 wt%
<small>IPC-TM-650 2.3.34</small>	
<small>JIS Z 3197 8.1.3</small>	
Halide Content	0.9 +/- 0.1 wt%
<small>JIS Z 3197 8.1.4.2.1</small>	
Water Extract Resistivity	> 1 x 10 ⁴ Ω-cm
<small>JIS Z 3197 8.1.1</small>	
Copper Corrosion Test	Pass
<small>IPC-TM-650 2.6.15</small>	
<small>JIS Z 3197 8.4.1</small>	
pH	2
Flash Point	17°C
Spread Factor	> 85% (SnPb)
<small>JIS Z 3197 8.3.1.1</small>	> 80% (SnCu3 and SnAg3.5)
Surface Finish	Shiny

Storage

Under proper storage condition, T-8 can be stored for about 6 months.

Packaging

Available in 20kg/carboy.

DISCLAIMER OF LIABILITY

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